

Title (en)
Adhesive packaging

Title (de)
Klebstoffkonfektionierung

Title (fr)
Confection de matière adhésive

Publication
EP 2377765 B1 20130605 (DE)

Application
EP 11160364 A 20110330

Priority
DE 102010003896 A 20100413

Abstract (en)
[origin: EP2377765A2] Packaging hot melt adhesive, preferably pressure-sensitive hot melt adhesive or adhesive substance as a material to be packaged in a plastic film at room temperature, comprises (a) melting the material to be packaged, (b) portion-wise dosing of the molten material on a cooling belt and cooling the material below its melting point to form material portions, (c) removing the material portions from the cooling belt and, (d) packaging the material portions in a plastic film. The cooling belt exhibits a textile carrier with threads, which forms at least a part of thermal conductors. Packaging hot melt adhesive, preferably pressure-sensitive hot melt adhesive or adhesive substance as a material to be packaged in a plastic film at room temperature, comprises (a) melting the material to be packaged, (b) portion-wise dosing of the molten material on a cooling belt and cooling the material below its melting point to form material portions, (c) removing the material portions from the cooling belt and, (d) packaging the material portions in a plastic film. The cooling belt exhibits a textile carrier with threads, which forms at least a part of thermal conductors, with which heat can be transferred from one flat side of the cooling belt on the opposite side of the carrier embedded in a polymer matrix so that the thermal conductors are covered largely at least on the side, which comes into contact with the material to be packaged.

IPC 8 full level
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